

Title (en)
METHOD AND STRUCTURES FOR ENHANCED TEMPERATURE CONTROL OF HIGH POWER COMPONENTS ON MULTILAYER LTCC AND LTCC-M BOARDS

Title (de)
VERFAHREN UND STRUKTUREN ZUR ERWEITERTEN TEMPERATURREGELUNG VON HOCHLEISTUNGSKOMPONENTEN AUF MEHRSCICHTIGEN LTCC- UND LTCC-M-LEITERPLATTEN

Title (fr)
PROCEDE ET STRUCTURE POUR AMELIORER LA REGULATION DE LA TEMPERATURE DE COMPOSANTS A GRANDE PUISSANCE SUR DES CARTES LTCC OU LTCC-M

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Application
EP 03783173 A 20031106

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Abstract (en)
[origin: WO2004045016A2] A multilayer ceramic circuit board comprises a core of high conductivity material such as metal and an overlying layer of electrically insulating ceramic having an outer surface. In accordance with the invention, a circuit board for receiving a high power component is provided with a thermal spreading layer on or near the outer surface and one or more thermal vias through the ceramic to thermally couple the spreading layer to the core. The vias and the spreading layer comprise electrically insulating thermally conductive materials. The resulting structure provides rapid heat dissipation for a high power component formed or mounted on or near the spreading layer.

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